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TECHNOLOGY TRANSFER

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Composable Distributed Acceleration

JUMP 2.0 ACE Center

Zhengya Zhang and team use homogeneous tiling and heterogeneous integration to scale up and scale out hardware to support larger models of more complex functions.

To accommodate the fast evolution of new models of larger size and higher complexity, they show modular chiplet integration can be a promising path to meet the growing needs.

SRC JUMP 2.0 RESEARCH PROGRAM

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